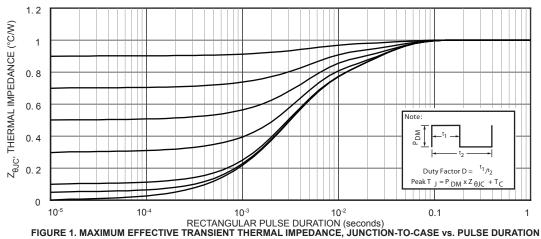
| Symbol           | Characteristic / Test Conditions    | Min | Тур  | Max | Unit  |
|------------------|-------------------------------------|-----|------|-----|-------|
| R <sub>eJC</sub> | Junction-to-Case Thermal Resistance |     |      | 1.0 | °C/W  |
| W <sub>T</sub>   | Package Weight                      |     | 0.07 |     | OZ    |
|                  |                                     |     | 1.9  |     | g     |
| Torque           | Maximum Mounting Torque             |     |      | 6.4 | lb∙in |
|                  |                                     |     |      | 0.7 | N·m   |

Microsemi reserves the right to change, without notice, the specifications and information contained herein.



## TYPICAL PERFORMANCE CURVES

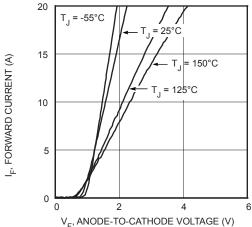


FIGURE 2, Forward Current vs. Forward Voltage

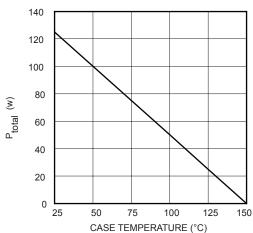


Figure 4. Maximum Power Dissipation vs. Case Temperature

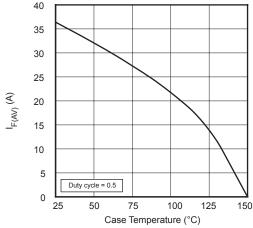


FIGURE 3, Maximum Average Forward Current vs. Case Temperature

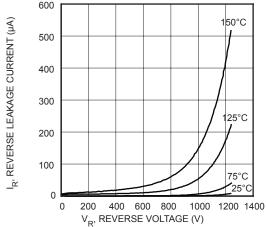
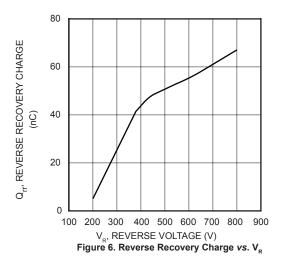
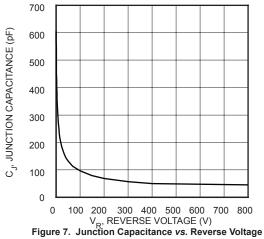
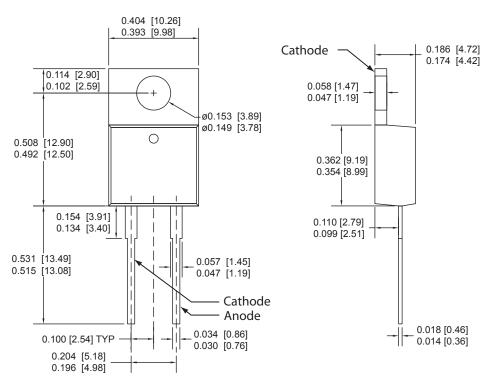


Figure 5. Reverse Leakage Currents vs. Reverse Voltage





## TO-220 (K) Package Outline



Dimensions in Millimeters and (Inches)

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